



RoHS

# Specification

Client Name :

客户名称 : \_\_\_\_\_

Client P/N :

客户品号 : \_\_\_\_\_

Product P/N :

产品型号: HL-C7035K29W18DB-1B3C(Ra1)-FC-CZ

Sending Date :

送样日期 : \_\_\_\_\_

Client approval 客户审核		Hongli approval 鸿利智汇审核	
Approval 核准	Audit 确认	Approval 核准	Audit 确认
			Confirmation 制作
<input type="checkbox"/> Qualified 接受	<input type="checkbox"/> Disqualified 不接受	DATE: 日期: 2018. 12. 29	梁依雯

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注:1. 此规格书以中英文方式书写,若有冲突以中文版本为准文本.

2. 此规格书的最终解释权归鸿利智汇集团股份有限公司

3. 此规格书的有效期限为两年,自盖章或签字之日起计算,期满时双方可以续签协议,但应采用书面形式



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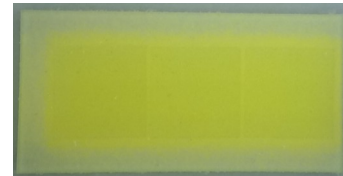


## Product naming rules 产品命名规则

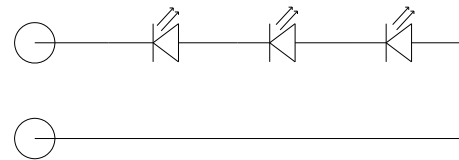
Under Development	●
Mass production	

HL-C 7035 K29 W 18 D B - 1B 3C (Ra1) -FC-CZ  
 1 2 3 4 5 6 7 8 9 10 11 12 13

- 1: 鸿利光电代码
- 2: 产品系列代码
- 3: 尺寸代码
- 4: 芯片代码
- 5: 表示发光颜色为白光
- 6: 表示最大使用的瓦数
- 7: 模具代码
- 8: 基板材质代码
- 9: 晶片并数
- 10: 晶片串数
- 11: 显色指数Ra70
- 12: 倒装工艺
- 13: 车载使用



Cathode



Anode



**ATTENTION**  
OBSERVE PRECAUTIONS  
FOR HANDLING  
ELECTROSTATIC  
DISCHARGE  
SENSITIVE  
DEVICES

## Features 特点

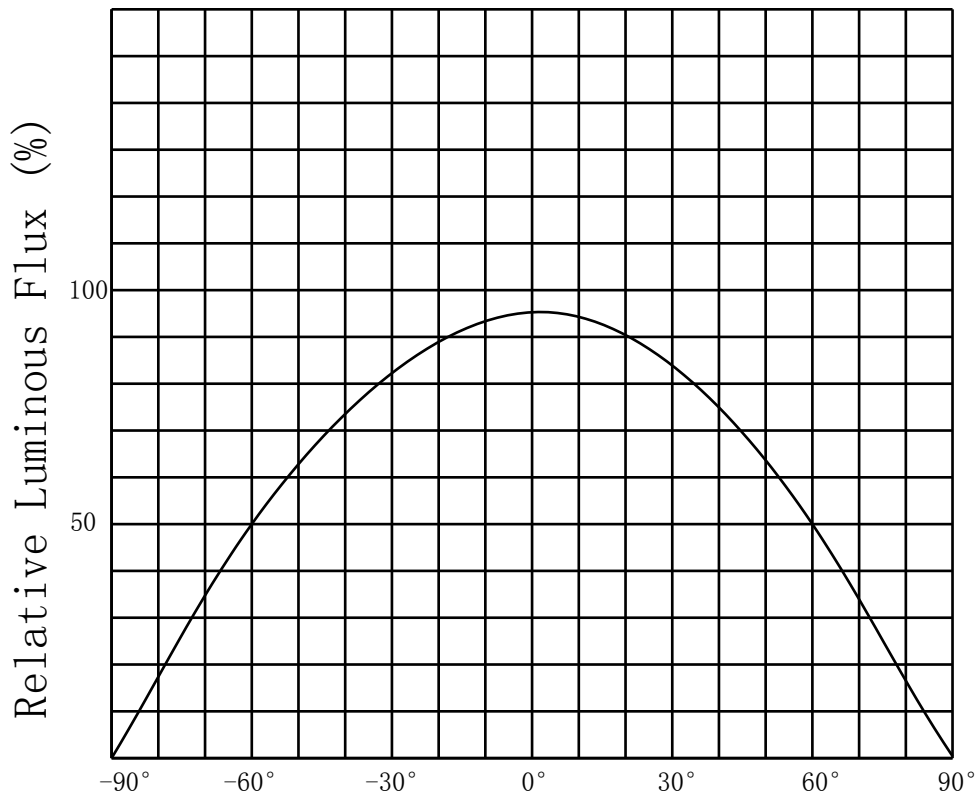
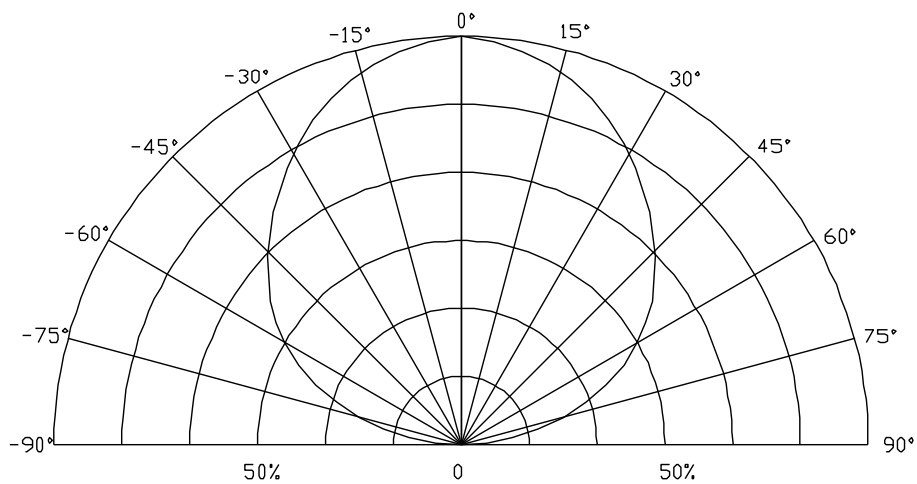
- Long operating life 寿命长
- High flux 光通量高
- Low voltage DC operated 低电压直流工作
- Cool beam, safe to the touch 冷光源，接触安全
- Instant light (less than 100ns) 瞬间点亮（小于100ns）
- No UV 无紫外线
- Flip Chip Technology 倒装芯片工艺
- RoHS compliant 符合RoHS标准
- Thermoelectric separation 热电分离
- Car use 车载使用



## Application range 应用范围

- CARLIGHT 车灯

## Radiation Pattern 辐射模式





## Specifications规范

### (1) Absolute Maximum Ratings at Ta=25°C

#### 在25°C时绝对极限条件

Parameter参数	Symbol符号	Rating 值	Units单位
Maximum Input power 最大输入功率	Pi	18	W
Maximum Forward Current 最大正向电流	I <sub>F</sub>	2000	mA
Forward voltage (正向电压)	V <sub>f</sub>	9.0 (tpy)	V
Junction Temperature 结温	T <sub>j</sub>	145	°C
View Angle (FWHM)-White 发光角度	—	120	degrees
Operating Temperature Range 工作温度	Topr	-40°C To +100°C	
Storage Temperature Range 储藏温度	Tstg	-40°C To +100°C	
ESD Sensitivity (HBM) 抗静电能力	ESD	Class 3B	
Reverse voltage (反向电压)	V <sub>r</sub>	not designed for reverse bias 不允许反向工作	

### Notes注:

- All high power emitter LED products mounted on aluminum metal-core printed circuit board, can be lighted directly, but we do not recommend lighting the high power products for more than 5 seconds without a appropriate heat dissipation equipment.  
所有高功率的发光LED产品安装在铝金属为核心印刷电路板，可直接点亮，但我们不建议在没有一个适当的散热设备时，照明高功率LED点亮超过5秒。
- Reflow soldering should not be done more than two times. The reflow temperature we recommend is 260°C, When the temperature exceeds 260 °C, the product failure of LED can be caused.  
回流焊不能超过两次,回流焊最高温度建议260°C，当温度超过260°C极大可能引起LED产品失效。
- The amplitude of the reverse voltage does not exceed 15V and the reverse current is less than 200uA. A maximum 15V reverse voltage for up to 10s is an acceptable beginning of life, one time, test.  
产品加反向电压时不能超过15V，反向电流不能超过200uA，而且通最大的反向电压时不能超过10s，测试不能超过1次。



## (2) Optical Characteristics at Ta=25°C

在Ta=25°C 时的典型光学特性

Tc (K)		1500mA光通量		2000mA光通量		显色指数 (Ra)
Min	Max	Min (lm)	Max (lm)	Min (lm)	Max (lm)	
5310	6020	1400	1650	1900	2100	70
		1650	1900	2100	2300	
5665	6530	1400	1650	1900	2100	
		1650	1900	2100	2300	

### Notes 注意事项:

1.The products after this specification refer to the parameters prevail, before the release of specification without refer to the above parameters.

此规格书发布日后生产的产品以上述参数为准，发布前生产的库存品不参考上述参数。

2.Tolerance of measurement of forward voltage±3%,Color-rendering index±2,luminous flux±5% .

不同标准源测试存在仪器公差：正向电压公差为±3%、显指公差为±2、光通量公差为±5%。

3.The parameters are just for reference,Do not order the request parameters.

参数仅供参考，不能作为下单时的参数要求。

## (3) Optical Electrical /Thermal Characteristics at Ta=25°

在Ta=25°C 时典型的电学/热学特性

IF (mA)	VF (V)			R (j-s) (°C/W)	Po (W)
	min	typ	max		
1500	8.4	8.92	9.2	0.73	13.4
2000	8.5	9.0	9.5	0.87	18

Products are tested and binned at a transient forward current(IF) with 1500mA. With the use of different IF, it may probably cause differences in CCT & forward voltage. Generally, with the increase of IF, the CCT will be raised as well. Thermal resistance test according to our standard .

该产品通过瞬态1500mA 点亮，分光分色.若使用不同电流，可能会引起色温及电压的变化，一般情况下，使用电流增加，色温会上升，热阻测试根据我司标准测试。

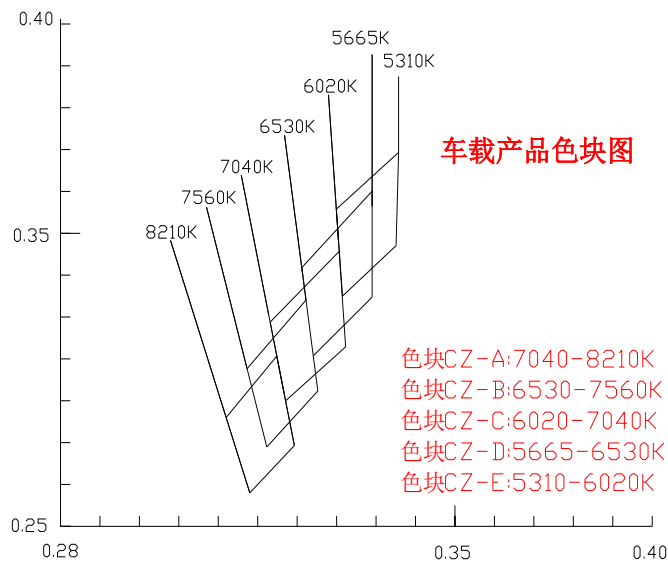


## Product bins 产品分级

### (1) Forward Voltage bins 电压分级

Min (V)	Max (V)	Min (V)	Max (V)
8.4	8.6	8.6	8.8
8.8	9.0	9.0	9.2

### (2) Chromaticity bins 色温分级



色块	CZ-A		CZ-B		CZ-C		CZ-D		CZ-E	
色温范围	7040-8210K		6530-7560		6020-7040		5665-6530		5310-6020	
中心色温	7560K		7040K		6530K		6020		5665	
坐标	X	Y	X	Y	X	Y	X	Y	X	Y
	0.2918	0.3062	0.2972	0.3177	0.303	0.3289	0.3114	0.3419	0.3197	0.3559
	0.2978	0.2881	0.3022	0.299	0.3069	0.3099	0.3144	0.3207	0.3215	0.3351
	0.3093	0.2993	0.3152	0.3124	0.3223	0.3229	0.3289	0.3348	0.3350	0.3469
	0.3049	0.3203	0.3122	0.334	0.3207	0.3457	0.3292	0.3601	0.3356	0.3692

#### Notes 注:

1. Products are tested and binned at a transient forward current (IF) with 1500mA. With the use of different IF, it may probably cause differences in CCT & forward voltage. Generally, with the increase of IF, the CCT will be raised as well.

该产品通过瞬态1500mA点亮，分光分色。若使用不同电流，可能会引起色温及电压的变化，一般情况下，使用电流增加，色温会上升。

2. Tolerance of  $\pm 0.005$  on x,y coordinates.

色坐标的测量误差允许在 $\pm 0.005$ 。

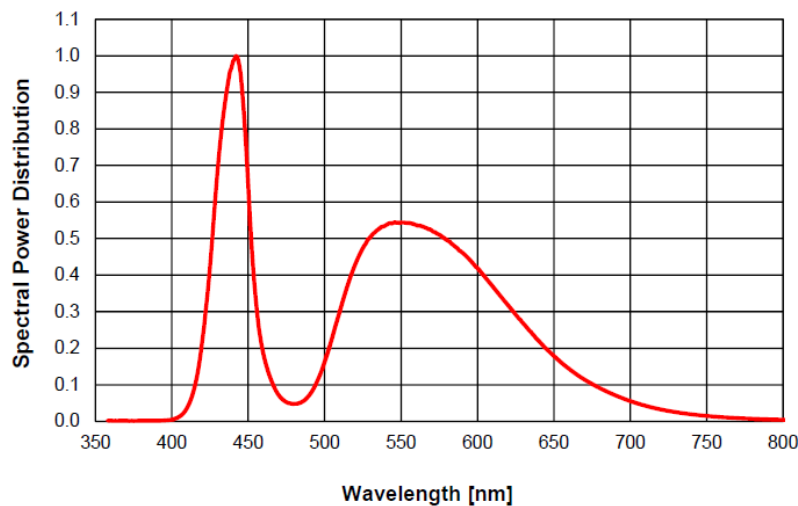
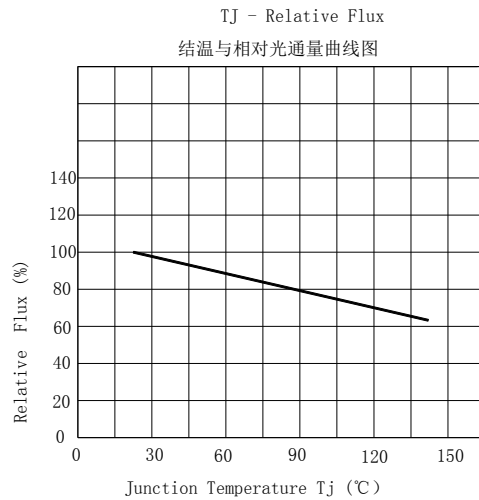
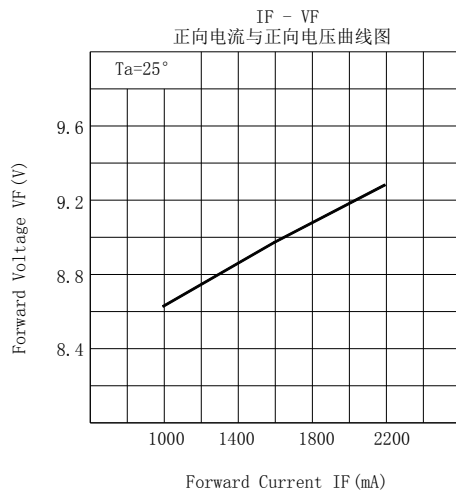
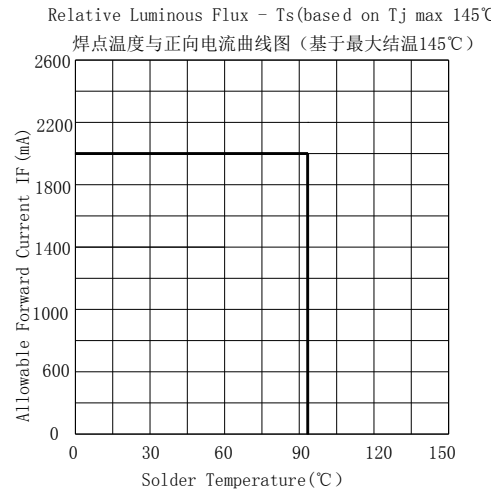
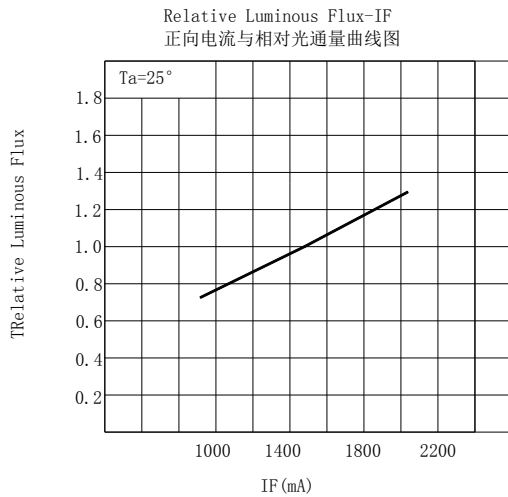
3. The chromaticity center refers to ANSI C78.377-2008.

色温分BIN参考ANSI C78.377-2008。



## Typical Optical/Electrical Characteristics Curves ( $T_a=25^\circ\text{C}$ Unless Otherwise Noted )

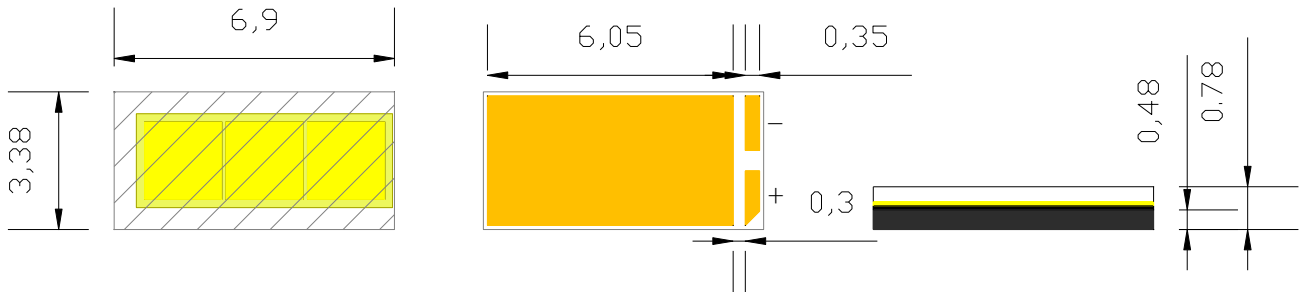
### 典型光学/电性特征曲线 ( $T_a=25^\circ\text{C}$ 除非另有注释)







## Package Dimensions 封装尺寸

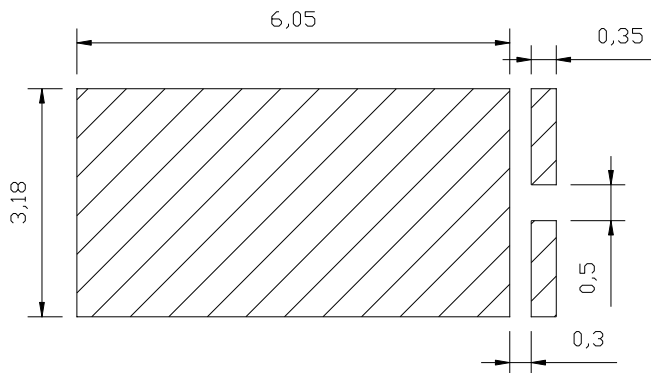


### Notes 注:

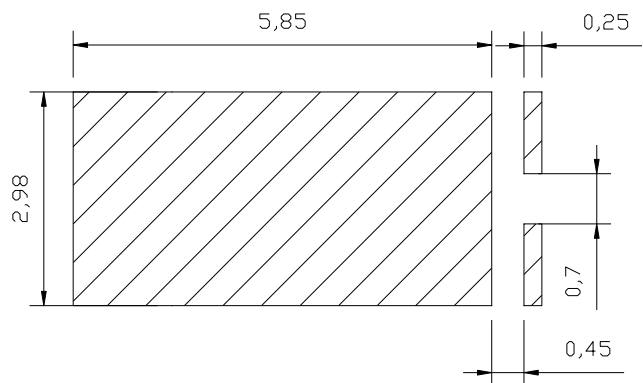
- All dimension units are millimeters.  
所有尺寸单位均为毫米。
- All dimension tolerance is  $\pm 0.1$ mm unless otherwise noted.  
所有尺寸误差是 $\pm 0.1$ 毫米除非另有说明。

## Welded plate and steel mesh Dimensions 焊盘及钢网尺寸

建议使用的基板焊盘尺寸



建议使用的钢网通孔尺寸



### Notes 注:

When the circuit configuration is not affected, suggested the increase in the middle of the copper area, or the connection between the middle and the pad and the negative electrode can improve the cooling performance of the product. It is recommended to use 0.1 mm thickness of steel mask.

在不影响电路配置时，建议增加中间焊盘覆铜区域，或中间焊盘和负极焊盘连接，能提高产品散热性能，建议使用热电分离的铜基板作为散热基板，建议使用钢网厚度为0.1mm。




**Label 标签**

TYPE: XXXXXXXXXX    QTY: XXXXX     $\Phi$ V: Luminous Flux rank  
产品型号                      包装数量                      光通量档次范围

IF: XXXX    TC: Color temperature    DATE: XXXX  
分选电流                      色温                      生产日期

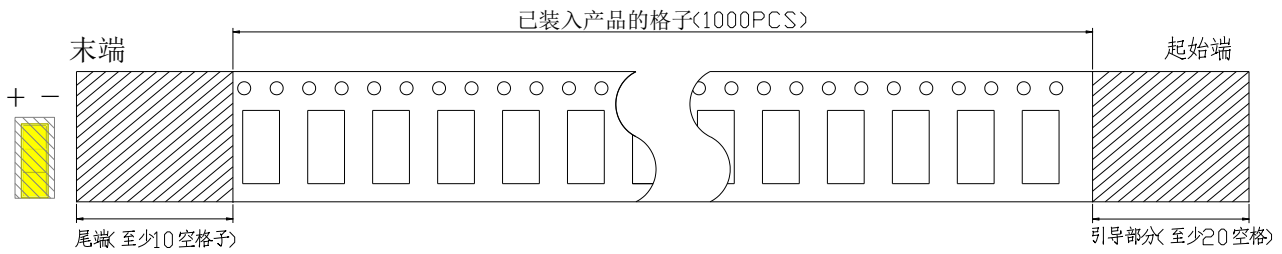
LOT.NO: Lot Number  
生产批号

	<b>HONGLITRONIC</b> 鸿利光电	<b>RoHS</b>
<b>TYPE:</b>		<b>QTY:</b>
<b>VF:</b>	<b>IF:</b>	<b><math>\phi</math>V:</b>
<b>TC:</b>	<b>X/Y:</b>	
<b>SDCM&lt;</b>	<b>Ra&gt;</b>	
<b>DATE:</b>	<b>LOT.NO:</b>	

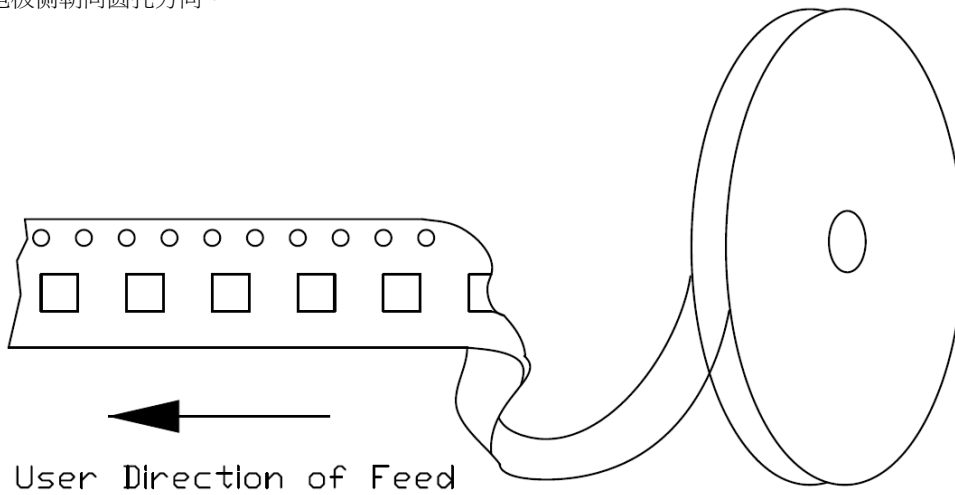


## Tape Specifications(Units:mm)包装规格

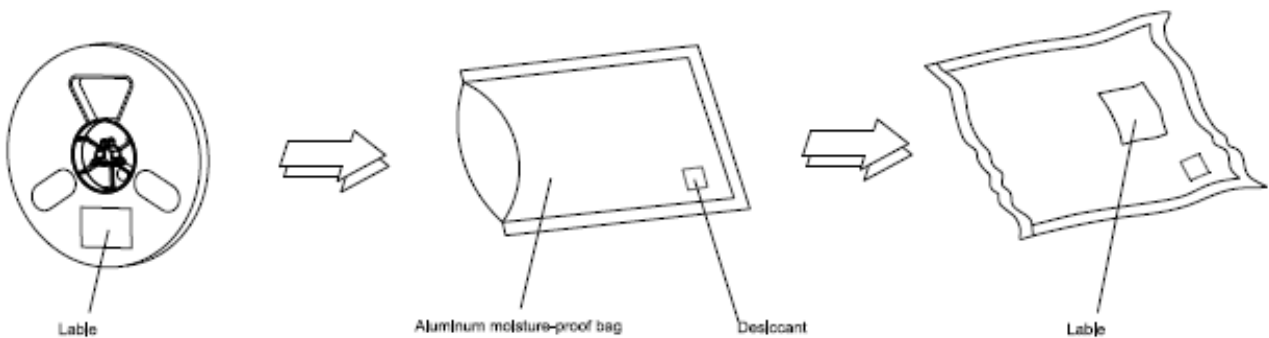
### (1)Reel package ( 1000 pcs/reel) 卷轴包装 ( 1000 pcs/卷) 载带空格前10后20



产品包装电极侧朝向圆孔方向。

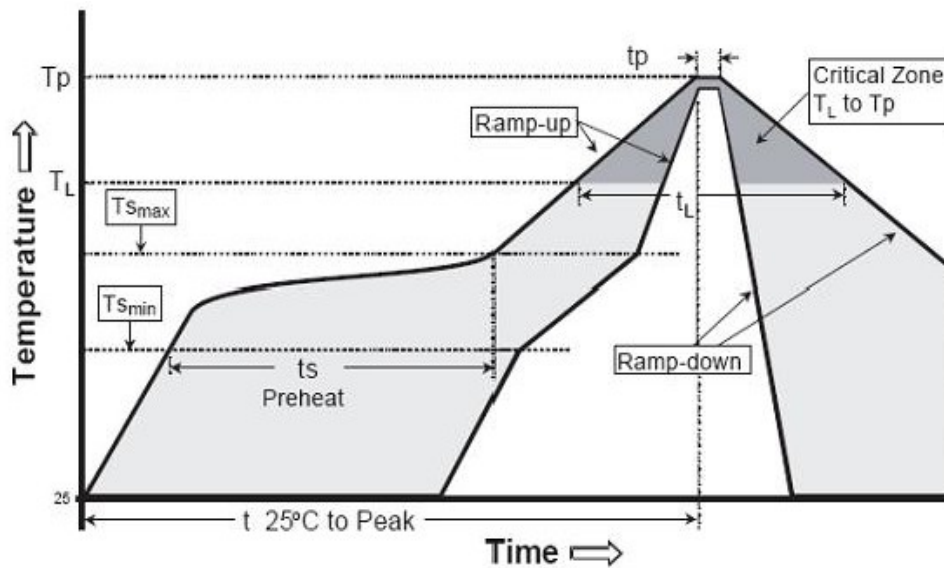


### (2)Moisture resistant packaging 防潮包装





## Reflow soldering instructions 回流焊说明



Profile Feature	Lead-Based solder	Lead-Free Solder
Average Ramp-Rate ( $T_{S_{max}}$ to $T_p$ )	3°C/second max	3°C/second max
Preheat: Temperature Min ( $T_{S_{min}}$ )	100°C	150°C
Preheat: Temperature Max ( $T_{S_{max}}$ )	150°C	200°C
Preheat: Time ( $t_{S_{min}}$ to $t_{S_{max}}$ )	60-120 seconds	60-180 seconds
Time Maintained Above: Temperature ( $T_L$ )	183°C	217°C
Time Maintained Above: Time ( $t_L$ )	60-150 seconds	60-150 seconds
Peak/Classification Temperature ( $T_p$ )	215°C	260°C
Time Within 5°C of Actual Peak Temperature ( $t_p$ )	10-15 seconds	20-40 seconds
Ramp-Down Rate	6°C/second max	6°C/second max
Time 25°C to Peak Temperature	6 minutes max	8 minutes max

### Note:

1. recommend to use a convection type reflow machine with 8 zones.

建议使用八温区回流焊机，参考曲线 145°-165°-185°-210°-220°-240°-260°-240° 运输速度90cm/min。

2. recommend to use Lead-Free Paste with a melting point between 210°C-220°C. For example M705.

建议使用熔点为210°C-220°C的无铅锡膏，建议使用千住 M705锡膏。

3. the reflow soldering time should not be more than 400s, all temperature means the temperature measured on the surface of the package body.

总的回流焊时间不要超过400s，所有温度均指在封装本体表面上测得的温度。

4. When using hot plate, the temperature is no more than 260 °C, the time is not more than 10 seconds.

当使用热板作业时，温度不超过260°C，时间不超过10秒。



## Use the matters needing attention(使用注意事项 )

### 一、储存(storage)：

为避免受潮的影响，我司建议产品在未开包装前储存条件为 5-30°C，相对湿度小于 60%；已开包装的 LED 光源请在 24H 内使用安装完毕，如未用完之产品，请进行除湿并抽真空后密封保存。开封超过一周或湿度卡发生变化时，请务必进行除湿，除湿条件：120°C±5°C，4H；产品密封保存有效使用期为一年。

To avoid moisture, we recommend storage conditions for the unopened LED +5 ~ +30 °C, relative humidity <60%. LED should be used within 24 Hrs. of opening the package. Please make sure to dehumidify and vacuum pack the remaining/ unused LED. Dehumidifying condition: +120 ° C ± 5 ° C, 04 Hrs. Effective age for the sealed led is one year.

### 二、组装注意事项(the assembly notes)：

焊接条件：此产品必须使用回流焊接的作业方式,回流曲线最高温度不可超过 260°C.作业或存放过程中不可有 1000g 以上的外力或尖锐物体作用于灯珠表面（如压力，摩擦等外力以及钳子镊子等工具），以免造成元件损伤；如果超出此使用条件，鸿利光电将不能保证产品的稳定性，如需使用超出的操作条件，请务必进行风险评。

Soldering Conditions：This product must be used reflow soldering practices, the maximum temperature of reflow should not exceed 260°C.Please make sure when soldering, there is no external force on the soldering surface (such as pressure, friction or sharp metal nails, etc.), to avoid gold wire deformation or damage and other abnormalities. If beyond recommended conditions, we cannot guarantee the LED stability, please do the risk assessment first.

### 三、防静电措施(anti-Static Measures)：

请采取足够的措施来防止静电产生，比如带静电环或防静电手指套等；每个制造工程关于产品（工厂、设备、机器、载波机和运输单位）应当连接地面，避免产品电气带电。

Please take adequate measures to prevent electrostatic generation, such as wearing electrostatic ring or anti-static fingerstall etc; any relative products like plant equipment, machinery, carrier and transportation units shall be connected to discharging unit/ ground. After assembly, please make sure to discharge Static Electricity with proper ESD equipment.

### 四、温度控制(temperature Control)：

为确保在组装时降低接触热阻，请注意在组装过程中，散热片采用良好品质的导热膏涂布均匀且分布面积合理，不可出现太少或高低不平等现象。散热介质需保证电介质耐压测试至少通过500V。

During assembly, please ensure that a good quality thermal paste is applied and distributed evenly over the surface. While using thermal pad (Heat Sink), make sure LED is firmly tightened and there is no gap between surfaces. The need to ensure the cooling medium dielectric withstand test at least through 500V.



## 五、驱动控制(drive control)：

本产品需使用恒流源进行驱动，且输出电流符合规格书上的功率使用范围，如需使用恒压源或其他使用条件，请进行使用效果风险评估。

Drive this product at constant current. Output current range specifications should be according to the operational and other conditions, as mentioned in data sheet. Before using a constant voltage source or altered specifications, other than recommended, please consider risk factors.

为使LED在稳定状态下工作，电路中必须串联保护电阻；

环境温度会影响到LED的可靠性，LED光源应当远离热源工作；

在LED固态照明设计中，不相容的挥发性有机化合物可能会降低照明系统的性能，缩短其使用寿命，因此在设计过程中请避免使用有机化合物

The circuit must be connected in series to ensure that the LED is working in a stable state.

The ambient temperature will affect the reliability of the LED, and the LED light source should be kept away from the heat source ;

In LED solid-state lighting design, the incompatibility of volatile organic compounds may degrade the performance of the lighting system, shorten its service life, therefore please avoid using organic compounds in the process of design .

## 六、其他(other)：

本产品不可在以下条件下使用，如果产品在以下条件下使用，评估其使用效果和风险是有必要的：

---直接或间接的打湿或受潮，比如淋雨等；

---被海水损害或侵蚀；

---被暴露于腐蚀性气体(如 Cl<sub>2</sub>, H<sub>2</sub>S、NH<sub>3</sub>、SO<sub>x</sub>、NO<sub>x</sub>等) ；

---被暴露于粉尘、液体或油；

Product is not suitable to use in following conditions;

—Direct or indirect wet / damp conditions, such as rain, etc;

—in contact with sea water and erosive materials;

—Exposed to corrosive gases (e.g., Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>x</sub>, NO<sub>x</sub>, etc.);

—Exposed to dust, liquids or oils;



## Reliability 可靠性测试

Test (测试项目)	Test Conditions (测试条件)	Test Duration (测试时间)	Decision criteria (判定标准)	Units Failed/ Tested (失败/测试数目)
Normal Temperature Operating Life (常温寿命)	25°C 2000mA 1008H	168H/1008H	VF≤1.1VF (初始) 光通量维持率≥85%	0/5PCS
High Temperature Operating Life (高温寿命)	85°C 2000mA 1008H	168H/1008H	VF≤1.1VF (初始) 光通量维持率≥85%	0/5PCS
Temperature Humidity Operating Life (高温高湿寿命)	85°C 85%RH 2000mA 1008H	168H/1008H	VF≤1.1VF (初始) 光通量维持率≥85%	0/5PCS
Temperature Cycle (温度循环)	-40°C--100°C 30min/5min/30min 500cycle	100cy/500cycle	无死灯、无外观不良	0/5PCS
Temperature Cycle (冷热冲击)	-40°C--100°C 30min/1min/30min 500cycle	100cy/500cycle	无死灯、无外观不良	0/5PCS



修订次数	修订人	修订内容	修订日期	版次
1	梁依雯	新建文件	2018. 12. 29	A/0
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